Global Molded Interconnect Substrate (MIS) Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Molded Interconnect Substrate (MIS) market size was valued at US$ 127 million in 2025 and is forecast to a readjusted size of US$ 342 million by 2032 with a CAGR of 15.4% during review period.

Molded Interconnect Substrate Technology (MIS) is a novel substrate solution that is ideal for mobile industry. It encompasses a wide range of solutions for the complex needs of IC package for mobile applications. With its embedded copper trace technology, it enable a finer line and space that is needed for high I/O count with smaller form factor. It also provides a robust Flip Chip assembly process. Another important feature of MIS substrate is copper filled-via and filled-pad technologies, which is significantly important for high frequency requirements, and improve thermal dissipation.

Currently, there are currently only three companies in the world that manufacture MIS substrates, China Taiwanese PPt, Chineses MiSpak Technology and Malaysian QDOS.

PPt now can supply 1 layer, 2 layer, 3 layer, 4 layer and 6 layer MIS substrates. MiSpak Technology supplies 1 layer and 2 layer MIS substrates. QDOS supplies 1 layer, 2 layer and 3 layer MIS substrates

The growth potential of MIS products in the substrate application market will come from network communication products such as servers and data centers, automotive electronic control equipment driven by electric vehicles and automotive intelligence, as well as 5G, AIoT and other applications. With the launch of these related products, the requirements for substrates used in semiconductor packaging will also increase

significantly, requiring a high degree of design flexibility, improved performance and high reliability.

In terms of advanced lead frame products, MIS manufacturers (PPt, MiSpak and QDOS) mainly supply products that are not limited to single-layer boards. PPt can also provide multi-layer board windable lead frame products for multi-chip packaging, which are products that are difficult for traditional lead frame suppliers to provide.

Currently the MIS substrates are mainly used in power/PMIC/analog, automotive electronics, RF/5G, Optical Image Stabilization (OIS), fingerprint recognition, third generation semiconductor, and LED, etc. Most of MIS substrates are used in power segment. For third generation semiconductor, MIS substrates are mainly used in GaN devices.

As technology continues to update, 5G applications require high speed, low latency technology and stable signals. With the demand for electronicization and intelligence, new applications continue to emerge in the consumer electronics and Industrial markets. This drives the performance requirements of Semiconductor chips to continue, towards high-speed computing, high performance, low loss, etc.

The development direction has also increased the demand for IC packaging substrates to have fine, narrow spacing, high heat dissipation and other characteeristics. The MIS substrates manufacturers have be cultivating its product production Technology capabilities for a long time and has currently developed Narrow pitch, winding, multi-layer board production technologies will be used in 5G, a lot, electric vehicles, etc.

In addition, in terms of consumer electronic smartphone applications, global well-known brand mobile phone manufacturers have a large presence in the market. When launching new mobile phones, the specifications of camera modules are continuously improved, and high-specification camera modules are constantly being. The penetration into new mobile phones has also accelerated the development of major Chinese mobile phone manufacturers due to theimpact of the Sino-US trade war. By introducing local raw Material supply, The MIS substrates manufacturers have laid out multiple plans in the field of mobile phone camera module applications. As new mobile phones are launched in the market one after another, it is expected that the market penetration rate of MIS substrates manufacturers products will increase.

This report is a detailed and comprehensive analysis for global Molded Interconnect Substrate (MIS) market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Molded Interconnect Substrate (MIS) market size and forecasts, in consumption value ($ Million), sales quantity (Million Units), and average selling prices (US$/Pcs), 2021-2032

Global Molded Interconnect Substrate (MIS) market size and forecasts by region and country, in consumption value ($ Million), sales quantity (Million Units), and average selling prices (US$/Pcs), 2021-2032

Global Molded Interconnect Substrate (MIS) market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (Million Units), and average selling prices (US$/Pcs), 2021-2032

Global Molded Interconnect Substrate (MIS) market shares of main players, shipments in revenue ($ Million), sales quantity (Million Units), and ASP (US$/Pcs), 2021-2026

The Primary Objectives in This Report Are:
To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Molded Interconnect Substrate (MIS)
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global Molded Interconnect Substrate (MIS) market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include PPt, MiSpak Technology, QDOS, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Molded Interconnect Substrate (MIS) market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

1 Layer MIS Substrate

2 Layer MIS Substrate

3 Layer MIS Substrate

4 Layer MIS Substrate

6 Layer MIS Substrate

Others

Market segment by Application

Analog Chip

Power IC

RF/5G

Fingerprint Sensor

OIS (Optical Image Stablization)

Others

Major players covered

PPt

MiSpak Technology

QDOS

Market segment by region, regional analysis covers
North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Molded Interconnect Substrate (MIS) product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Molded Interconnect Substrate (MIS), with price, sales quantity, revenue, and global market share of Molded Interconnect Substrate (MIS) from 2021 to 2026.

Chapter 3, the Molded Interconnect Substrate (MIS) competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Molded Interconnect Substrate (MIS) breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026.and Molded Interconnect Substrate (MIS) market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Molded Interconnect Substrate (MIS).

Chapter 14 and 15, to describe Molded Interconnect Substrate (MIS) sales channel, distributors, customers, research findings and conclusion.

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